

ULTRA MINIATURE RELAY SIGNAL RELAY

FTR-C2 Series

RoHS Compliance

■ FEATURES

Dimensions of large contact gap relay

Height: 11.8 mm maximum (THT)

12 mm maximum (SMT)

Length: 20.2 mm maximum Width: 10 mm maximum

Conforms to IEC60950 / EN60950 / UL1950/ CSA C22.2

No.950 spacing & high breakdown voltage

Recognized by UL/CSA and Bsi

UL: File E63615 Vol. 2 Sec.4

CSA: Master contract 169663 Certificate 1088921

Clearance: 2.0 mm (between open contacts,

coil and contacts, contact sets)

Creepage: 2.0 mm (between open contacts,

coil and contacts, contact sets)

 HIGH RELIABILITY Bifurcated contacts

- Low power consumption 300 mV
- RoHS Compliant since production

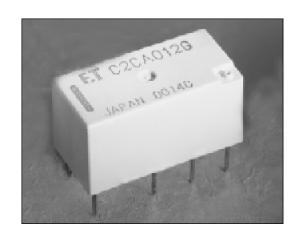
■ ORDERING INFORMATION

[Example] $\frac{\text{FTR-C2}}{\text{(a)}} \quad \frac{\text{C}}{\text{(b)}} \quad \frac{\text{A}}{\text{(c)}} \quad \frac{\text{012}}{\text{(d)}} \quad \frac{\text{G}}{\text{(e)}}$

(a)	Series Name	FTR-C2	
(b)	Termianl Apprearance	C: Through hole type G: Surface mount type	
(c)	Operation Function	A: Standard Type	
(d)	Coil Number	Nominal Voltage	
(e)	Contact Material	G: Silver alloy	

Remarks: Actual marking on relay would not carry code FTR and be as below:

Ordering code Actual marking FTR-C2CA03G \rightarrow C2CA03G



■ COIL DATA CHART

Standard type

Model	Nominal Voltage	Coil Resistance (±10%)	Must Operate Voltage	Must Release Voltage	Nominal Operating Power (±10%)
FTR-C2 (C) (A) 003-G	3 VDC	30.0 Ω	2.25 VDC	0.3 VDC	300 mW
FTR-C2 (C) (A) 005-G	5 VDC	83.3 Ω	3.75 VDC	0.5 VDC	300 mW
FTR-C2 (C) (A) 012-G	12VDC	480.0 Ω	9.00 VDC	1.2 VDC	300 mW

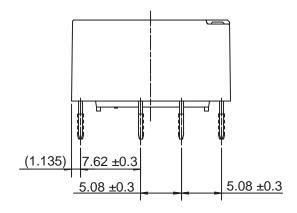
Note: All values in the table are measured at 20°C.

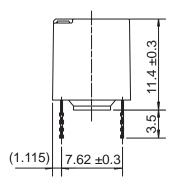
■ SPECIFICATIONS

Item			FTR-C2CA ()G FTR-C2GA-()G		
	Arrangement		2 Form C		
Contact	Material		Silver alloy		
	Resistance (i	nitial)	Max. 150m ohm (at 1A 6VDC)		
	Max. Switchin	ng Power	62.5AV / 30W		
	Max. Switchin	ng Voltage	250VAC, 220 VDC		
	Max. Switchin	ng Current	1 A		
Coil	Operating Te	mperature	-40° C to + 85° C (no frost)		
	Max. Allowa	ble Voltage	150% nominal voltage (at 20°C)		
Time - Malaca	Operate Time	Э	Max. 15ms (at nominal voltage, without bounce		
Time Value	Release Time	e (without diode)	Max. 15ms (at nominal voltage, without bounce		
	Resistance (a	at 500 VDC)	Min. 1,000M ohm		
		Between open contacts	1,500VAC, 1 minute		
	Dieelectric Strenght	Between adjacent contacts	1,500VAC, 1 minute		
Insulation	Chonghi	Between coil and contacts	2,000VAC, 1 minute		
	Surge Strength	Between open contacts	2,500V (at10/700micros)		
		Between adjacent contacts	2,500V (at10/700micros)		
		Between coil and contacts	2,500V (at10/700micros)		
Life	Mechanical		10x10 ⁶ operations min. (at 10Hz)		
	Electrical (res	sistive load)	100x10 ³ operations min. at 1A, 30VDC, 0.5Hz 100x10 ³ operations min. at 0.1A, 48VDC, 0.5Hz 100x10 ³ operations min. at 0.3A, 125VDC, 0.5Hz		
Vibration	Misoperation		10 to 55 Hz at double amplitude of 3.3 mm		
Resistance	Endurance		10 to 55 Hz at double amplitude of 5 mm		
Shock Resistance	Misoperation		Min. 300 m/s ²		
	Endurance		Min. 1,000 m/s ²		
UL / CSA	Contact Ratin	ng	0.3A 125 VAC 1A 30VDC 0.3 110VDC		
IEC060950 UL1950 C22.2 No.950 EN60950	Insulation Cla	ass	Supplementary Insulation		
	Working Volt	age	250 V		
	Pollution Deg	ree	2 (outside)	1 (inside)	
	Clearance		2.0 mm (outside)	2.0 mm (inside)	
	Creepage Dis	stance	2.5 mm (outside)	2.0 mm (inside)	

■ DIMENSIONS AND SCHEMATICS

Through hole type



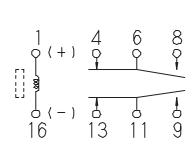


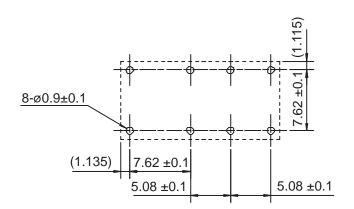
Unit: mm

■ TERMINAL DESIGNATIONS

■ RECOMMENDED MOUNTING PAD

(Bottom view de-energized position)

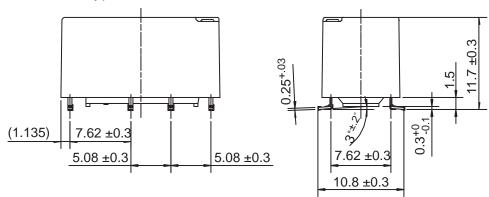




Unit: mm

■ DIMENSIONS AND SCHEMATICS

Surface mount type

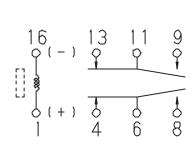


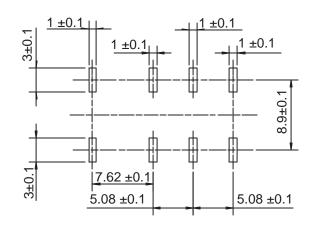
Unit: mm

■ TERMINAL DESIGNATIONs

■ RECOMMENDED MOUNTING PAD

(Top view de-energized position)

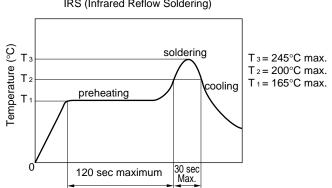




Unit: mm

■ RECOMMENDED SOLDERING CONDITIONS (TEMPERATURE PROFILE)

IRS (Infrared Reflow Soldering)



Note:

- 1.Temperature profiles show the temperature of PC board surface.
- 2. Please perform soldering test with your actual PC board before mass production, since the temperatures of PC board surfaces vary according to the size of PC board, status of parts mounting and heating method.

Fujitsu Components International Headquarter Offices

Fujitsu Component Limited

Gotanda-Chuo Building 3-5, Higashigotanda 2-chome, Shinagawa-ku

Tokyo 141, Japan Tel: (81-3) 5449-7010 Fax: (81-3) 5449-2626

Email: promothq@ft.ed.fujitsu.com

Web: www.fcl.fujitsu.com

North and South America

Web: www.fcai.fujitsu.com

Fujitsu Components America, Inc. 250 E. Caribbean Drive Sunnyvale, CA 94089 U.S.A. Tel: (1-408) 745-4900 Fax: (1-408) 745-4970 Email: marcom@fcai.fujitsu.com

Europe

Fujitsu Components Europe B.V.

Diamantlaan 25 2132 WV Hoofddorp Netherlands

Tel: (31-23) 5560910 Fax: (31-23) 5560950 Email: info@fceu.fujitsu.com Web: www.fceu.fujitsu.com

Asia Pacific

Fujitsu Components Asia Ltd. 102E Pasir Panjang Road #04-01 Citilink Warehouse Complex

Singapore 118529 Tel: (65) 6375-8560

Fax: (65) 6273-3021 Email: fcal@fcal.fujitsu.com www.fcal.fujitsu.com

© 2004 Fujitsu Components America, Inc. All company and product names are trademarks or registered trademarks of their respective owners. Rev. 09/21/2004.